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Notice of Allowability	Application No.	Applicant(s)	
	10/758,302	BASHO ET AL.	
	Examiner	Art Unit	
	Joseph Nguyen	2815	
The MAILING DATE of this communication ap All claims being allowable, PROSECUTION ON THE MERITS I herewith (or previously mailed), a Notice of Allowance (PTOL-8 NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT of the Office or upon petition by the applicant. See 37 CFR 1.3	S (OR REMAINS) CLOSED in to the state of the	his application. If not included ication will be mailed in due cou	rse. <b>THIS</b>
1. This communication is responsive to the application filed	<u>on 1/15/2004</u> .	·	
2. X The allowed claim(s) is/are 1-17.			
3. $\boxtimes$ The drawings filed on <u>15 January 2004</u> are accepted by	the Examiner.		
4. ☑ Acknowledgment is made of a claim for foreign priority  a) ☑ All b) ☐ Some* c) ☐ None of the:  1. ☑ Certified copies of the priority documents ha  2. ☐ Certified copies of the priority documents ha  3. ☐ Copies of the certified copies of the priority of International Bureau (PCT Rule 17.2(a)).  * Certified copies not received:  Applicant has THREE MONTHS FROM THE "MAILING DATE noted below. Failure to timely comply will result in ABANDON THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.  5. ☐ A SUBSTITUTE OATH OR DECLARATION must be sub INFORMAL PATENT APPLICATION (PTO-152) which g  6. ☐ CORRECTED DRAWINGS (as "replacement sheets") m  (a) ☐ including changes required by the Notice of Draftsperior of the priority of the paper No./Mail Date	ve been received.  ve been received in Application documents have been received in Application documents have been received in Application documents have been received in Application to file and Application document of this application.  In the submitted document or in Application document document or in Application documents document	No  In this national stage application reply complying with the requiration of the Office action of	ements
Identifying indicia such as the application number (see 37 CFF each sheet. Replacement sheet(s) should be labeled as such in	n the header according to 37 CFR	1.121(d).	
<ol> <li>DEPOSIT OF and/or INFORMATION about the department of attached Examiner's comment regarding REQUIREMEN</li> </ol>	TOUSIT OF BIOLOGICAL MATER T FOR THE DEPOSIT OF BIOL	RIAL Must de Sudmitted, Note OGICAL MATERIAL.	e the
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Attachment(s) 1. ☑ Notice of References Cited (PTO-892)	5. Notice of Info	rmal Patent Application (PTO-1	52)
2. Notice of Draftperson's Patent Drawing Review (PTO-948		nmary (PTO-413), ail Date	
3. Information Disclosure Statements (PTO-1449 or PTO/SE Paper No./Mail Date 1/15/2004	3/08), 7. Examiner's A	mendment/Comment	
4. Examiner's Comment Regarding Requirement for Deposi		tatement of Reasons for Allowa	nce
of Biological Material	9. 🔲 Other		
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## **DETAILED ACTION**

## Allowable Subject Matter

Claims 1-17 are allowed.

The following is an examiner's statement of reasons for allowance:

The reference (s) of record do not teach or suggest, either singularly or in combination at least the limitation of "a through metal member made of copper buried from an upper surface to another surface in a central portion of the frame like substrate, and copper layers joined onto the one and other surfaces of the substrate and the through metal member so as to cover the one and other surfaces thereof' for claim 1, "a through metal member made of diamond and a silver-copper alloy copper buried from an upper surface to another surface in a central portion of the frame like substrate, and copper layers joined onto the one and other surfaces of the substrate and the through metal member so as to cover the one and other surfaces thereof' for claim 2; "wherein in the heat releasing member, a plurality of through metal members made of a plate like substrate made of a matrix of tungsten or molybdenum and copper to another surface, copper layers are joined at least to one and other surfaces of a portion in which the through metal members of the substrate are buried, and a cross section area of each of the through metal members is gradually increased from the center side of the substrate to a joint portion with the copper layers" for claim 10; "wherein in the heat releasing member, a plurality of through metal members made of a copper are buried from the

one surface of the mounting portion of a plate like substrate made of a matrix of tungsten or molybdenum and copper to the other surface, copper layers are joined at least to the one surface of a portion of the substrate positioned inside the frame and on the other surface of a portion in which the through metal members are buried, and an arithmetical mean roughness Ra on the one surface of the portion positioned inside the frame and the side face of the heat releasing member is each 0.05  $\mu$ m  $\leq$  Ra  $\leq$  30  $\mu$ m" for claim 11.

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Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

US Patent 5,783,857 to Ziegner et al. discloses an IC package.

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Joseph Nguyen whose telephone number is (571) 272-1734. The examiner can normally be reached on Monday-Friday, 7:30 am- 4:30 pm. If attempts to reach the examiner by telephone are unsuccessful, the examiner's

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supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306 for regular communications.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

JN March 12, 2005

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PRIMARY EXAMINER